

## Feature

- High Luminous Output Green LED Lamp
- Chip Technology — AlInGaP
- Green Diffused 5mm Packages
- Viewing Angle **40** Degree (Reference)

## SDL-2R3KG-LT1

## Specification

### Absolute Maximum Ratings

Item	Symbol	Absolute Maximum Rating	Unit
DC Forward Current	$I_F$	30	mA
Peak Pulsed Forward Current ※	$I_{FP}$	60	mA
Reverse Voltage	$V_R$	5	V
Power Dissipation	$P_d$	75	mW
Operating Temperature	$T_{opr}$	-40 ~ +100	°C
Storage Temperature	$T_{stg}$	-55 ~ +100	°C
Solder Dipping Temperature	$T_{sld}$	260°C for 5 sec	

※  $I_{FP}$  = Pulse Width  $\leq$  10 ms, Duty Ratio  $\leq$  1/10

### Electrical / Optical Characteristics

$T_a = 25^\circ\text{C}$

Item	Symbol	Condition	Min	Typ	Max	Unit
Forward Voltage	$V_F$	$I_F=20\text{mA}$		2.10	2.40	V
Reverse Current	$I_R$	$V_R=5\text{V}$			100	$\mu\text{A}$
Luminous Intensity	$I_V$	$I_F=20\text{mA}$	85	180		mcd
Dominant Wavelength	$\lambda_d$	$I_F=20\text{mA}$		572		nm
Peak Wavelength	$\lambda_p$	$I_F=20\text{mA}$		575		nm
Spectral Half Width	$\Delta \lambda_{1/2}$	$I_F=20\text{mA}$		11		nm



Electrostatic Sensitive Devices

## Luminous Intensity Bin Table

**IF=20mA**

Rank name	Min (mcd)	Max (mcd)
<b>EF</b>	<b>85</b>	<b>140</b>
<b>GH</b>	<b>140</b>	<b>240</b>
<b>JK</b>	<b>240</b>	<b>400</b>

※ Tolerance for each bin limit is  $\pm 15\%$

## Color Bin Table

**IF=20mA**

Rank name	Min (nm)	Max (nm)
<b>H06</b>	<b>566</b>	<b>568</b>
<b>H07</b>	<b>568</b>	<b>570</b>
<b>H08</b>	<b>570</b>	<b>572</b>
<b>H09</b>	<b>572</b>	<b>574</b>
<b>H10</b>	<b>574</b>	<b>576</b>
<b>H11</b>	<b>576</b>	<b>578</b>

※ Tolerance for each bin limit is  $\pm 1\text{nm}$

### Note

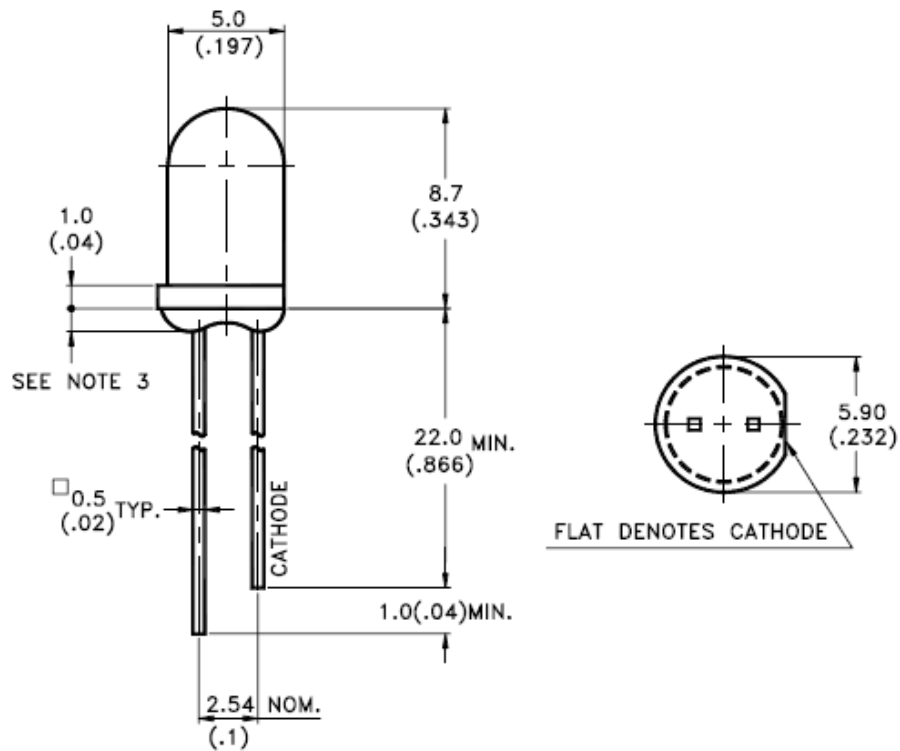
1. One delivery will include several color ranks and  $I_v$  ranks of products.  
The quantity-ratio of the different rank is decided by Sander.
2. Bin Name typed on the Label: IV RANK + Color Rank.
3. Sander has the right to update the information without notice.  
Please double confirm the Spec details before place an order.



Electrostatic Sensitive Devices

## Outline Dimensions

### Lamps with Standoffs



Item	Materials
Resin	Epoxy Resin
Lead Frame	Ag Plating on SPCC

### Note

1. All Dimensions are in Millimeters
2. Tolerance is +/- 0.25mm unless otherwise noted.
3. Protruded resin under flange is 1.0mm max.



Electrostatic Sensitive Devices

## Electrical-Optical Characteristics

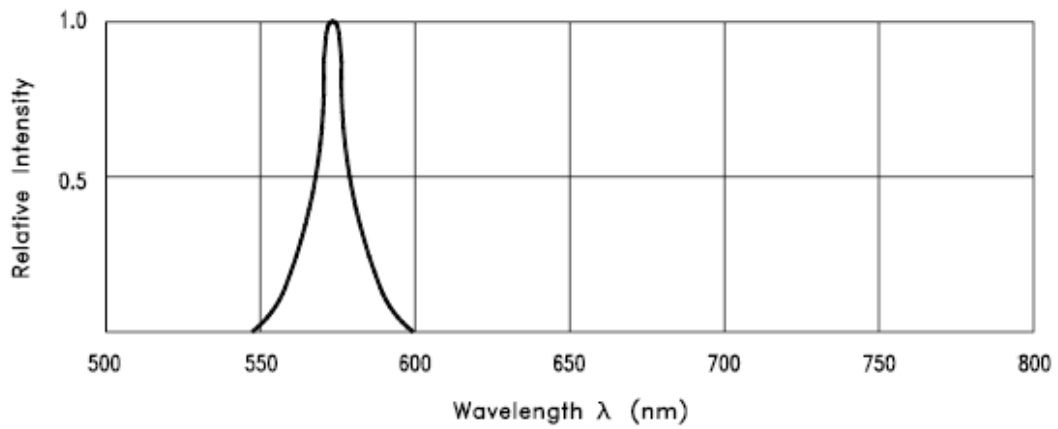


Fig.1 Relative Intensity vs. Wavelength

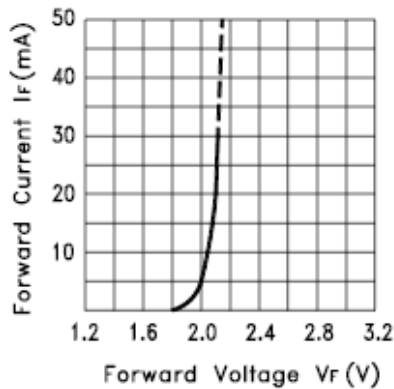


Fig.2 Forward Current vs. Forward Voltage

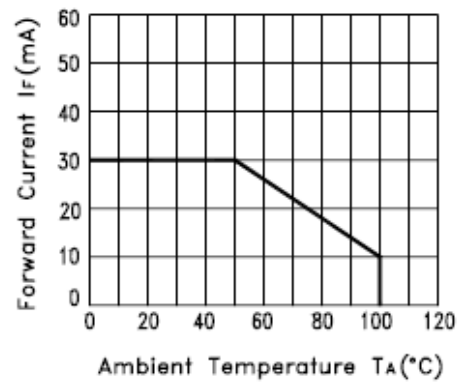


Fig.3 Forward Current Derating Curve

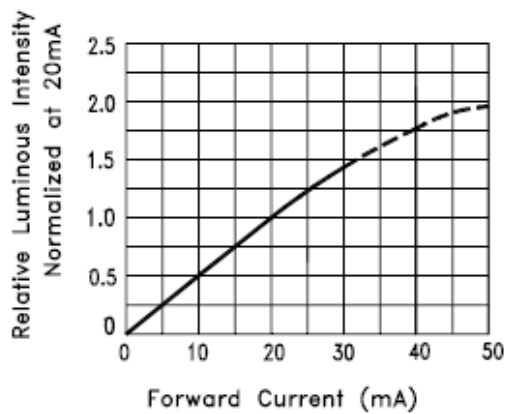


Fig.4 Relative Luminous Intensity vs. Forward Current

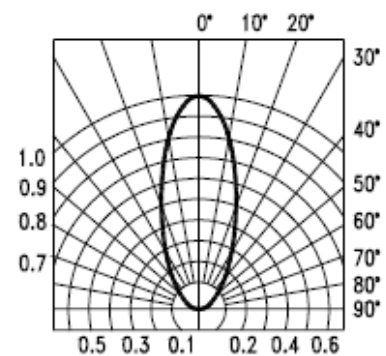


Fig.5 Spatial Distribution



## Soldering Conditions - Lamp Type LED

- Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended
- Recommended soldering conditions

<b>Dip Soldering</b>	
<b>Pre-Heat</b>	100°C Max.
<b>Pre-Heat Time</b>	60 sec. Max.
<b>Solder Bath Temperature</b>	260°C Max.
<b>Dipping Time</b>	10 sec. Max.
<b>Dipping Position</b>	No lower than 3mm from the base of the epoxy bulb.

<b>Hand Soldering</b>	
	<b>30 Series</b>
<b>Temperature</b>	300°C Max.
<b>Soldering time</b>	3 sec. Max.
<b>Position</b>	No closer than 3mm from the base of the epoxy bulb.

- Do not apply any stress to the lead, particularly when heated
- The LEDs must not be repositioned after soldering
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the User will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. Sander's LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause LED failure.

